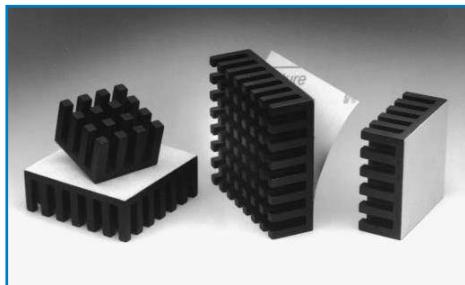
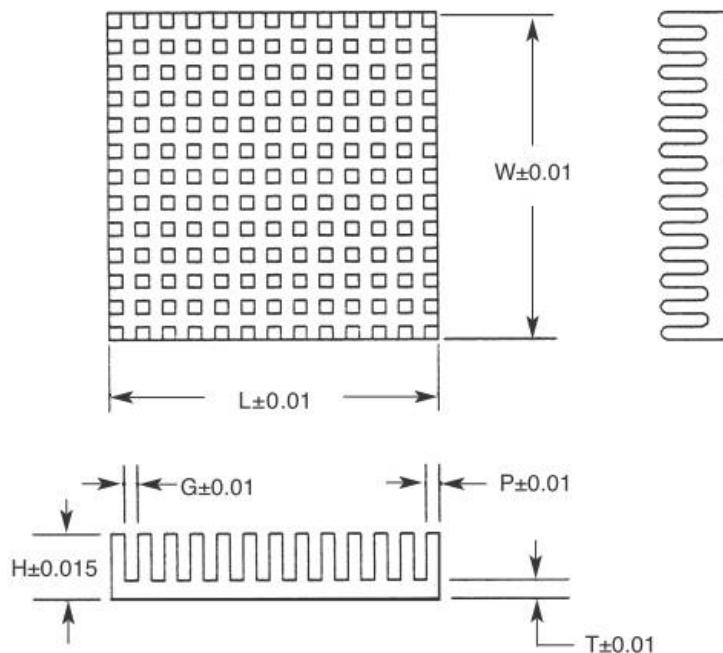


ADHESIVE PEEL AND STICK HEAT SINKS



- With pre-applied adhesive, just peel off the release liner and press onto the component
- Reduces assembly costs; no more messy adhesives or greases required
- Excellent mechanical bond
- Thermally optimized pin fin
- Omnidirectional
- Adhesive shear strength at 100°C is 36psi (a one inch square heat sink would require a 36lb. force to remove heat sink)
- Applicable for BGA, PGA, PLCC, and QFP packages



PART NUMBER***	SIZE				PIN FIN CONFIGURATION			THERMAL RESISTANCE CASE TO AMBIENT* °C/WATTS	
	(W)	(L)	(H)	T	P	G	FIN MATRIX	NATURAL CONVECTION**	FORCED CONVECTION @ 400 LFPM
BDN09-3CB/A01	0.91	0.91	.355	.09	.069	.072	7x7	26.9	9.6
BDN09-6CB/A01			.605	.10	.132	.128	4x4	24.5	7.7
BDN10-3CB/A01	1.01	1.01	.355	.09	.083	.072	7x7	26.4	8.0
BDN10-5CB/A01			.555	.10	.111	.114	5x5	20.8	6.3
BDN11-3CB/A01	1.11	1.11	.355	.09	.076	.072	8x8	20.9	7.2
BDN11-6CB/A01			.605	.10	.119	.128	5x5	18.5	5.7
BDN12-3CB/A01	1.21	1.21	.355	.09	.060	.081	9x9	19.6	6.8
BDN12-5CB/A01			.555	.10	.105	.114	6x6	16.5	5.2
BDN13-3CB/A01	1.31	1.31	.355	.09	.074	.081	9x9	16.1	6.0
BDN13-5CB/A01			.555	.10	.125	.114	6x6	14.9	4.7
BDN14-3CB/A01	1.41	1.41	.355	.09	.067	.081	10x10	16.2	5.6
BDN14-6CB/A01			.605	.10	.128	.128	6x6	13.1	4.2
BDN15-3CB/A01	1.51	1.51	.355	.09	.062	.081	11x11	15.1	4.5
BDN15-5CB/A01			.555	.10	.118	.114	7x7	11.9	3.8
BDN16-3CB/A01	1.61	1.61	.355	.09	.072	.081	11x11	13.5	4.5
BDN16-6CB/A01			.605	.10	.119	.128	7x7	10.6	3.5
BDN17-3CB/A01	1.71	1.71	.355	.09	.065	.072	13x13	11.5	3.8
BDN18-3CB/A01	1.81	1.81	.355	.09	.072	.072	13x13	10.8	3.5
BDN18-6CB/A01			.605	.10	.128	.114	8x8	8.1	2.8
BDN19-3CB/A01	1.91	1.91	.355	.09	.069	.072	14x14	9.9	2.9
BDN21-3CB/A01	2.11	2.11	.355	.09	.064	.072	16x16	8.5	2.6

All dimensions are in inches.

NOTES:

*Thermal resistance of adhesive tape is included.

**Thermal resistance values based on power density of 3 watts/in²

***Part numbers listed for standard black anodized heat sinks with CTS adhesive tapes.